

AUG 15 2005

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U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT		Docket Number: 10191/3268
Application Number 10/655,839	Filing Date Sept. 4, 2003	Examiner Dung Anh LE
Invention Title SEMICONDUCTOR COMPONENT HAVING A FIRST EARLIER STRUCTURE DIFFERING FROM A SECOND EARLIER STRUCTURE		Inventors Hubert BENZEL et al.

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

1. In accordance with the duty of disclosure under 37 C.F.R. § 1.56 and in conformance with the procedures of 35 U.S.C. §§ 1.97 and 1.98 and M.P.E.P. § 609, attorneys for Applicant hereby bring the following references to the attention of the Examiner. These references are listed on the attached modified PTO Form No. 1449. It is respectfully requested that the information be expressly considered during the prosecution of this application, and that the references be made of record therein and appear among the "References Cited" on any patent to issue therefrom. The filing of this Information Disclosure Statement and the enclosed PTO Form No. 1449, shall not be construed as an admission that the information cited is prior art, or is considered to be material to patentability as defined in 37 C.F.R. § 1.56(b).
2. A copy of the references listed on the modified PTO Form 1449 are enclosed herewith or as otherwise indicated.
3. Applicant's attorney certifies that each item of information contained in the information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of information disclosure statement.

08/16/2005 MWOLDGE1 00000016 110600 10655839

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4. The Commissioner is hereby authorized to charge payment of the 37 C.F.R. §1.17(p) (submission of an information disclosure statement under §1.97(c)) fee of **\$180.00** and any additional fees that may be required to the deposit account of **Kenyon & Kenyon**, deposit account number **11-0600**. A copy of this communication is enclosed for charging purposes.

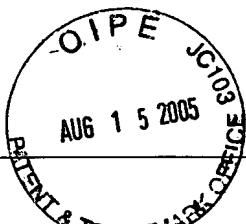
Dated:

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**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

ATTY. DOCKET NO.
10191/3268

SERIAL NO.
10/655,839

APPLICANT
Hubert Benzel et al.

FILING DATE
Sept. 4, 2003

GROUP
2818

U. S. PATENT DOCUMENTS

EXAMINER INITIAL	PATENT NUMBER	PATENT DATE	NAME	CLASS	SUBCLASS	FILING DATE*

* - If pertinent

FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
						YES NO
	1 088 785	April 4, 2001	EP			X
	100 46 622	April 4, 2002	DE			X
	WO 03/016203	Feb. 27, 2003	PCT			X
	WO 02/36484	May 10, 2002	PCT			X

OTHER DOCUMENTS

EXAMINER INITIAL		AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.
		R. W Tjeskstra et al. "Multi-walled Microchannels: Free-standing Porous Silicon Membrane For Use In Mu TAS", Journal of Microelectromechanical Systems, IEEE INC., Bd. 9 Nr. 4, Dec. 2000, pp. 495-501.
		H. Artmann et al., "Monocrystalline SI Membranes For Pressure Sensors Fabricated By A Novel Surface Micromachining Process Using Porous Silicon", Proceedings of Spie, Mernes Components and Applications for Industry, Automobiles, Aerospace and Communication II, January 28-29, 2003, San Jose, CA, Bd. 4981, pp. 65-70.
		G. Lammel et al. "Free-Standing, Mobile 3D Porous Silicon Microstructures", Sensors and Actuators A., Bd. 85, No. 1-3, August 25, 2000, pp. 356-360.

EXAMINER	DATE CONSIDERED
EXAMINER: Initial if citation considered, whether or not citation is in conformance with M.P.E.P. 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	